



648.43481VC5

ITW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: N. FUKUTOMI, et al.
Serial No: 10/705,706
Filed: NOVEMBER 10, 2003
Title: FABRICATION PROCESS OF SEMICONDUCTOR PACKAGE
AND SEMICONDUCTOR PACKAGE
Group AU: 2813
Examiner: Laura M. Schillinger
Confirm. No: 5226
Allowed: SEPTEMBER 19, 2006

AMENDMENT UNDER 37 CFR 1.312

Mail Stop: ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

December 12, 2006

Sir:

Please amend the above-identified application, subsequent to issuance of the Notice of Allowance and Fee(s) Due mailed September 19, 2006, and prior to payment of the Issue Fee, as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.

12/25/06
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OK